



SMART CARD PERSONALIZATION AND WRAPPING MACHINE

MODEL
SCPW3000A

Efficient and accurate,
professional smart card packaging solutions



Beyond Smart Manufacturing

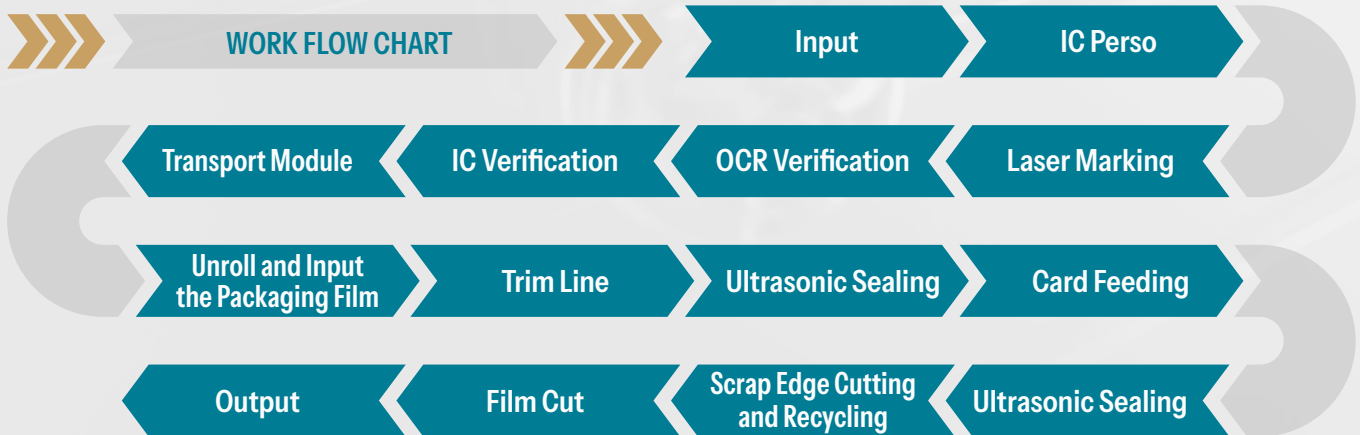
SMART CARD PERSONALIZATION AND WRAPPING MACHINE

SCPW3000A



Smart card personalized and packaging machine is a high-end production line that integrates M2M and SIM card (2FF/3FF/4FF) personalized data writing and packaging.

On the basis of the SCM3000 equipment, it innovatively supports the personalized data writing of the SIM card (2FF, 3FF, 4FF), and integrates the packaging function of the telecom card industry standard. The integration of M2M chips with traditional telecommunications card production processes allows users to create greater value with minimal investment.



Application Scope

IoT / Smart City Management
Security Field / Mobile Payment

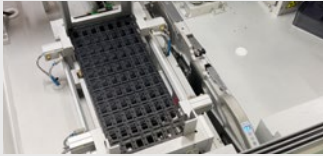
Application Materials

Intelligent devices in more than ten packaging forms such as QFN, DFN, VSOP8 and 2FF/3FF/4FF SIM cards

ADVANTAGES

- 01** High-precision identification and positioning system ensures that each smart card can be accurately packaged.
- 02** Multi-functional compatible design, suitable for different sizes, materials of smart card packaging needs.
- 03** High speed and stable operation performance, greatly improve production efficiency, reduce labor costs.
- 04** Intelligent monitoring interface, real-time feedback production data, easy quality control and maintenance management.

CONFIGURATIONS AND FUNCTIONS



Input Module

- Tray input : up to 20pcs of trays can be loaded.
- Tape input : tape in 12mm is supported, 8mm, 16mm and 24mm is extensible; Compatible with tape rolls in 1000pcs and 3000pcs.



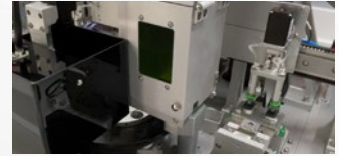
Chip Turning Module

- Configure 2 chip storage stations.
- Tit can achieve automatic rotation of 90° forward, 90° reverse and 180° reverse by identifying the mark point on the chip.



IC Perso Module

- Standard configuration: 16 perso stations with 4pcs of PIOTEC 4 IN 1 contact readers.
- Extensible configuration: 32 perso stations with 8pcs of PIOTEC 4 IN 1 contact readers. Chip encoding and remaking online is supported. ISO7816, Serial port, Bluetooth, SPI and I2C protocols are supported.



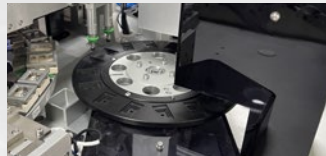
Laser Marking Module

- Configure 1 set of 20W fiber laser. Piotec-owned laser marking technology is adopted, and surface information in 2 chips can be marked at the same time, which improves marking efficiency.
- Configure 1 set of extractor.



IC Verification Module

- Standard configuration : 2 verification stations with 1pcs of PIOTEC contact reader . The internal information in 2 chips can be read and verified at the same time, ensuring 100% accuracy.



OCR Verification Module

- Configure a set of 5 million pixel industrial camera (including light source).
- Configure a set of OCR software. Surface information of chips can be recognized and verified.



Reject Module

- Configure 3 reject boxes, Optional 8 reject boxes. Chips which fail to be encoded or marked can be rejected automatically and stored in different categories to reduce material loss and labor costs.



Output Module

- Tray input : up to 20pcs of trays can be loaded.
- Tape input : Compatible with tape rolls in 1000pcs and 3000pcs. Compatible with tray and tape output for chips packaging.



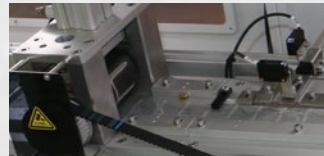
Unrolling Module

- Configure a set of $\phi 75\text{mm}$ pneumatic expansion shaft and packaging film connecting device, the roll packaging film can be quickly replaced within 3 minutes.



Trim Line Module

- Configure a set of circular hob to support the production of ant lines on the packaging film; Correct input materials.



Three Sides Welding Module

- Configure a set of professional mold, which used for ultrasonic welding three sides of the packaging film.



Card Feeding Module

- Configure a conveyor device, the SIM card produced in the previous "personalized" process can be transferred to the card issuing module of the packaging machine;
- Configure a set of step card feeding mechanism, the card can be accurately pushed into the packaging film;
- Compatible with many forms of card transfer.



OCR Verification Module

- Configure a set of 5 million pixel industrial camera (including light source) , the card sequence can be detected before the chip is pushed into the packaging film.



Single Side Welding Module

- Configure a set of professional mold, which used for ultrasonic welding one side of the packaging film.



Output Module

- Automatic winding device is configured to support the collection of packaged products.

MAXIMUM THROUGHPUT

Maximum production capacity(pcs/h)



TECHNICAL SPECIFICATION

DIMENSION : (1900×1650×1800mm) (3600mm×950mm×1500mm)
WEIGHT : 600KG、576KG
POWER SUPPLY : 220V(-5% ~ +10%), 50Hz, 4.5KW
NOISE : <75dB

OPERATION TEMPERATURE : 23°C±3°C
OPERATION HUMIDITY : 50%±10%
COMPRESSED AIR : 0.5Mpa, 300L/min



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